# **ON Semiconductor**

# Is Now



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# **Power MOSFET**

# 40 V, 0.48 m $\Omega$ , 533 A, Single N-Channel

#### **Features**

- Small Footprint (8x8 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Q<sub>G</sub> and Capacitance to Minimize Driver Losses
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

## **Typical Applications**

- Power Tools, Battery Operated Vacuums
- UAV/Drones, Material Handling
- BMS/Storage, Home Automation

## **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V <sub>DSS</sub>	40	V
Gate-to-Source Voltage			V <sub>GS</sub>	±20	V
Continuous Drain	Steady State	T <sub>C</sub> = 25°C	I <sub>D</sub>	533	Α
Current R <sub>θJC</sub> (Note 2)	State	T <sub>C</sub> = 100°C		377	
Power Dissipation	Steady	T <sub>C</sub> = 25°C	P <sub>D</sub>	245	W
R <sub>θJC</sub> (Note 2)	State	T <sub>C</sub> = 100°C		122.7	
Continuous Drain	Steady State	T <sub>A</sub> = 25°C	I <sub>D</sub>	76	Α
Current R <sub>θJA</sub> (Notes 1, 2)	State	T <sub>A</sub> = 100°C	1	54	
Power Dissipation	Steady	T <sub>A</sub> = 25°C	$P_{D}$	5.0	W
$R_{\theta JA}$ (Notes 1, 2) State		T <sub>A</sub> = 100°C	1	2.5	
Pulsed Drain Current	T <sub>A</sub> = 25	°C, t <sub>p</sub> = 10 μs	I <sub>DM</sub>	900	Α
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Source Current (Body Diode)			Is	204.5	Α
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 53 A)			E <sub>AS</sub>	2058	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 2)	$R_{\theta JC}$	0.61	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	30.2	

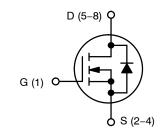
- 1. Surface-mounted on FR4 board using a 1 in<sup>2</sup> pad size, 1 oz. Cu pad.
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.



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V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
40 V	0.48 m $\Omega$ @ 10 V	533 A



**N-CHANNEL MOSFET** 



#### MARKING DIAGRAM



A = Assembly Location
WL = 2-digit Wafer Lot Code

Y = Year Code WW = Work Week Code

#### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS				I			
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /	I <sub>D</sub> = 250 μA, ref to 25°C			13.19		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>					10	
		V <sub>DS</sub> = 40 V	T <sub>J</sub> = 125°C			250	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = 20 V				100	nA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_D = 250 \mu A$		2.0		4.0	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>	I <sub>D</sub> = 250 μA, ref to 25°C			-8.28		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 50 A		0.39	0.48	mΩ
Forward Transconductance	9FS	V <sub>DS</sub> =5 V, I <sub>D</sub> = 50 A			233		S
Gate Resistance	$R_{G}$	T <sub>A</sub> = 25°C			1.0		Ω
CHARGES, CAPACITANCES & GATE RESIS	TANCE				•		
Input Capacitance	C <sub>ISS</sub>			11800		pF	
Output Capacitance	C <sub>OSS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 20 V			7030		
Reverse Transfer Capacitance	C <sub>RSS</sub>				199		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 20 V; I <sub>D</sub> = 50 A			187		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>				29.7		
Gate-to-Source Charge	Q <sub>GS</sub>				46.6		
Gate-to-Drain Charge	$Q_{GD}$				38.2		
SWITCHING CHARACTERISTICS, V <sub>GS</sub> = 10	V (Note 4)				•		
Turn-On Delay Time	t <sub>d(ON)</sub>				33.6		
Rise Time	t <sub>r</sub>	$V_{GS}$ = 10 V, $V_{DS}$ = 20 V, $I_{D}$ = 50 A, $R_{G}$ = 2.5 $\Omega$			27.9		ns
Turn-Off Delay Time	t <sub>d(OFF)</sub>				86.0		
Fall Time	t <sub>f</sub>				32.3		
DRAIN-SOURCE DIODE CHARACTERISTIC	s						1
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 50 A	T <sub>J</sub> = 25°C		0.757	1.2	
			T <sub>J</sub> = 125°C		0.603		V
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = 0 \text{ V, dIS/dt} = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 50 \text{ A}$			105		ns
Charge Time	t <sub>a</sub>				60		
Discharge Time	t <sub>b</sub>				45		
Reverse Recovery Charge	Q <sub>RR</sub>				274		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: pulse width  $\leq 300~\mu s$ , duty cycle  $\leq 2\%$ .

4. Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**

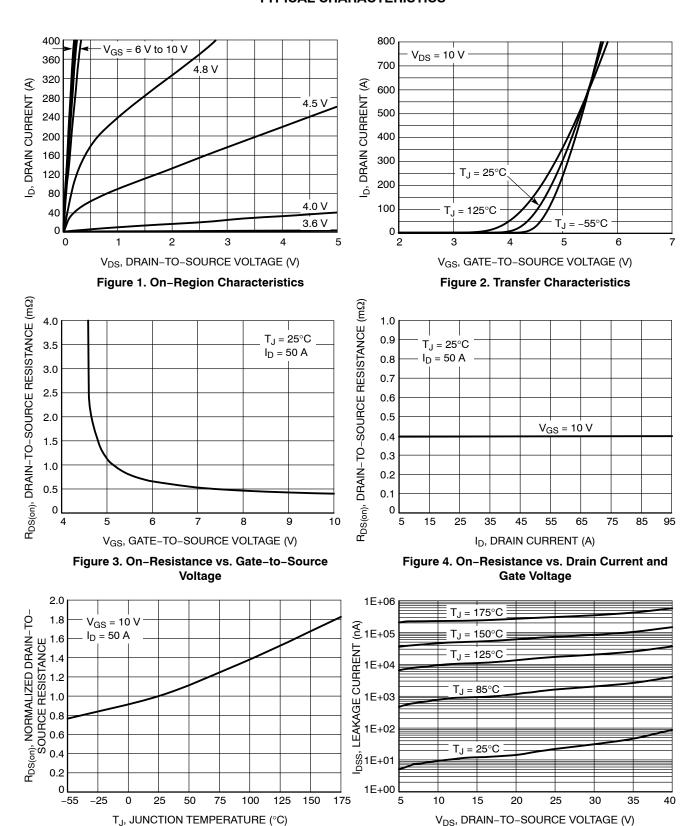


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Voltage

#### **TYPICAL CHARACTERISTICS**

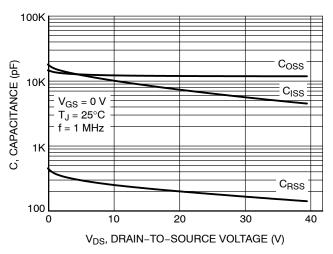


Figure 7. Capacitance Variation

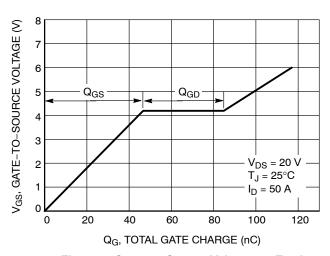


Figure 8. Gate-to-Source Voltage vs. Total Charge

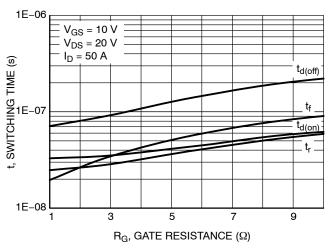


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

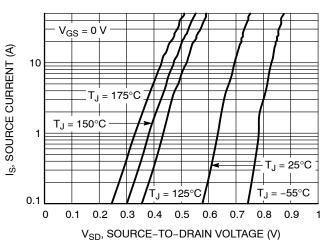


Figure 10. Diode Forward Voltage vs. Current

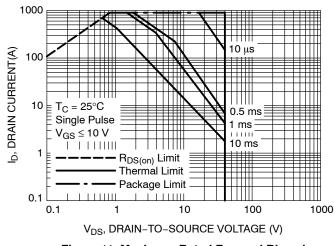


Figure 11. Maximum Rated Forward Biased Safe Operating Area

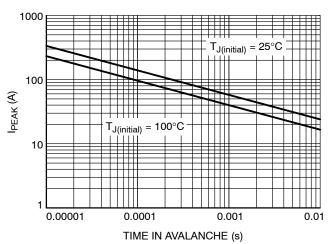


Figure 12. I<sub>PEAK</sub> vs. Time in Avalanche

#### **TYPICAL CHARACTERISTICS**

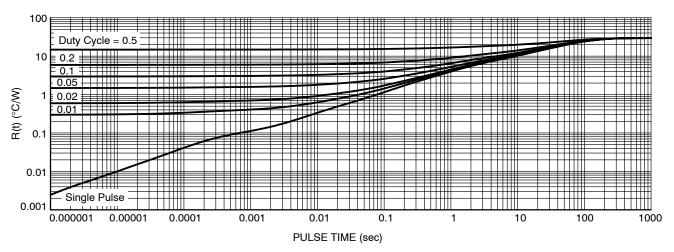


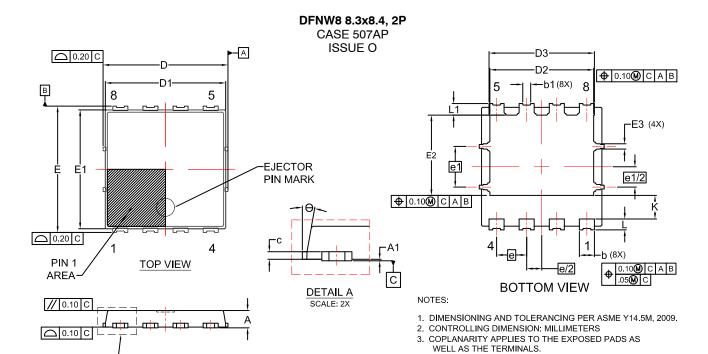
Figure 13. Thermal Characteristics

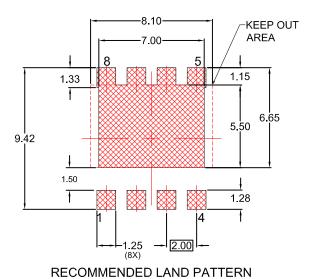
## **DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
NTMTS0D6N04CTXG	0D6N04C	POWER 88 (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **PACKAGE DIMENSIONS**





FRONT VIEW

SEE DETAIL A

MILLIMETERS DIM MIN. NOM. MAX. 1.00 1.20 Α 1.10 Α1 0.00 0.05 b 0.90 1.00 1.10 0.43 0.53 0.63 b1 0.23 0.28 0.33 D 8.20 8.30 8.40 D1 7.90 8.00 8.10 D2 6.80 6.90 7.00 D3 6.90 7.00 7.10 8.30 8.40 8.50 E1 7.80 7.90 8.00 E2 5.24 5.34 5.44 0.35 0.45 E3 0.25 е 2.00 BSC e/2 1.00 BSC 2.70 BSC e1 e1/2 1.35 BSC 1.57 1.70 Κ 1.50 0.64 0.74 0.84 0.87 L1 0.67 0.77 0° 12° θ

4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH,

"A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

PROTRUSIONS, OR GATE BURRS.

5. SEATING PLANE IS DEFINED BY THE TERMINALS.

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